**FOR IMMEDIATE RELEASE**

**[SAMTEC LOGO] November 2020**

**Samtec Virtually Showcases Latest Silicon-to-Silicon Interconnect Solutions at SC20**

**New Albany, IN:** Samtec Inc., a privately held $800 MM global manufacturer of a broad line of electronic interconnect solutions, will virtually showcase and demonstrate their latest high-performace interconnect solutions at SuperComputing 2020.

HPC system designers must balance increasing throughput, scalability and density demands with cost and time-to-market. Samtec addresses these challenges with industry-leading design expertise, system optimization, and innovative architectural solutions ideally suited for HPC applications. Key technologies will be featured during SC20 via the Exhibitor Forum, Virtual Demonstations and Featured Products.

**SC20 Exhibitor Forum**

[**Brian Niehoff**](https://blog.samtec.com/post/author/brian/), Technical Marketing Engineer at Samtec, will present the topic [***Thermal Management of HPC Hardware Architectures via Immersion Cooling***](https://sc20.supercomputing.org/presentation/?id=exforum122&sess=sess329).

As computing power increases, air cooled systems cannot meet current thermal requirements in HPC architectures. Immersion cooling economically combats system heat, noise, power consumption and compute density. In this presentation, Samtec will discuss both novel immersion cooling techniques and observed results from testing across its interconnect product portfolio.

**SC20 Virtual Demonstrations**

* PCIe® 4.0 Over Fiber Adapter Card: Samtec and Dolphin
* UCLA’s Ocean High-Throughput Processor in the CMS Experiment at the CERN Large Hadron Collider
* Thermal Management of HPC Hardware Architectures via Immersion Cooling
* PLDAs latest PCIe® 5.0 Evaluation and Development Platform

**SC20 Featured Products**

Key Samtec high-performance interconnect solutions will be featured at SC20. From front-panel to the backplane, HPC system designers can count on key solutions from Samtec including:

* Si-Fly™ 112 Gbps PAM4 Low-Profile High-Density Cable System
* NovaRay® 112 Gbps PAM4 Extreme Density Arrays
* FireFly™ Micro Flyover System™
* AcceleRate® HD, AcceleRate® HP and AcceleRate® Cable Interconnect Solutions

The Exhibitor Forum, Virtual Demonstrations and Featured Products will occur virtually from November 17-19, 2020.

For more information on Accelerating HPC Interconnect via Silicon-to-Silicon Solutions, please visit [www.samtec.com/SC20](http://www.samtec.com/SC20).

**About Samtec**Founded in 1976, Samtec is a privately held, $800 MM global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. Samtec Technology Centers are dedicated to developing and advancing technologies, strategies and products to optimize both the performance and cost of a system from the bare die to an interface 100 meters away, and all interconnect points in between. With 40+ international locations and products sold in more than 125 different countries, Samtec’s global presence enables its unmatched customer service. For more information, please visit [http://www.samtec.com](http://www.samtec.com/).

**Samtec, Inc.**

**P.O. Box 1147**

**New Albany, IN 47151-1147**

**USA**

**Phone: 1-800-SAMTEC-9 (800-726-8329)**

[**www.samtec.com**](http://www.samtec.com)

###

**PR Contact:**

Matt Burns

[matthew.burns@samtec.com](mailto:matthew.burns@samtec.com)

812-944-6733